Overview

HP 470 G9 17 inch Notebook PC



1. Internal Microphone (2)

- 2. Webcam LED
- 3. Webcam
- 4. Clickpad

Left

- 5. Headphone/microphone combo jack
- SuperSpeed USB Type-C[®] 5Gbps signaling rate (Data Transfer Only)
- 7. HDMI 1.4 (Cable sold separately)
- 8. SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)



Overview



Right

- 1. Power Button
- 2. Power Connector
- **3.** Super Speed USB Type- A 5Gbps signaling rate (USB 3.2 Gen 1)
- 4. Hard Drive LED

- 5. Power LED
- 6. Fingerprint Sensor



Overview

AT A GLANCE

- Preinstalled with Windows 11 Pro, Windows Home or FreeDOS
- Choice of 12th generation Intel[®] Core[™] i7, i5 and i3 processors
- NVIDIA® GeForce® MX550 (2 GB GDDR6 dedicated) (Optional)
- Fast dual channel DDR4 SODIMM memory up to 32 GB
- Choice of 17.3" diagonal HD, Ultra Wide Viewing Angle FHD, Non-Touch screen
- Full size, optional backlit keyboard and clickpad with Precision Touchpad Supported certified
- Choice of solid state drives up to 1TB
- TPM2.0, Touch Fingerprint reader
- Supports wireless options for connectivity on the go including gigabit-data rate Wi-Fi 6
- Optimize your video calls with an HD camera and temporal noise reduction that adjusts the lighting to your environment.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP 470 G9 17 inch Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 11 Pro¹ Windows 11 Pro Education ¹ Windows11 Home – HP recommends Windows 11 Pro for business ¹ Windows 11 Home Single Language – HP recommends Windows 11 Pro for business ^{1,2} Windows 11 Home Education – HP recommends Windows 11 Pro for business ¹ FreeDOS3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

2. This computer is preinstalled with Windows 11 Home Single Language.

PROCESSORS

Processor ^{3,4,5,6} Core	Cores Number of P-cores	Number of E-cores	Threads	L3 Cache	Max Turbo Frequency		Base Frequency		
		P-COLES E-COL	L-LUICS	5	Latile	P-cores	E-cores	P-cores	E-cores
Intel® Core™ i7-1255U	10	2	8	12	12MB	4.7 GHz	3.5 GHz	1.7 GHz	1.2 GHz
Intel® Core™ i5-1235U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.3 GHz	0.9 GHz
Intel® Core™ i3-1215U	6	2	4	8	10MB	4.4 GHz	3.3 GHz	1.2 GHz	0.9 GHz

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy. HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated

Intel[®] UHD Graphics ⁷ Intel[®] Iris[®] X^e Graphics ^{7,8}

Discrete

NVIDIA® GeForce® MX550 (2 GB DDR6 dedicated) 9

Supports

Support HD decode, DX12, HDMI 1.4b⁷

7. HD content required to view HD images.

8. Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

9. Integrated graphics depends on processor. NVIDIA[®] Optimus[™] technology requires an Intel processor, plus an NVIDIA[®] GeForce[®] discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA[®] Optimus[™] technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAY

Non-Touch

43.9 cm (17.3") diagonal, HD+ (1600 x 900), Anti-Glare LED SVA, 250 nits, 60% NTSC, eDP 1.2 w/o PSR ^{7,10} 43.9 cm (17.3") diagonal, FHD (1920 x 1080), Anti-Glare LED UWVA, 250 nits, 45% NTSC, eDP 1.2 w/o PSR ^{7,10} 43.9 cm (17.3") diagonal FHD (1920 x 1080), Anti-Glare WLED UWVA, 300 nits, 72% UWVA eDP 1.4+PSR2 slim 60Hz Narrow Bezel ^{7,10}

Displays support

HDMI v1.4b up to 1920x1080 60Hz

Display Size (Diagonal)

17.3" 43.9 cm (17.3")

7. HD content required to view HD images.10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.



STORAGE AND DRIVES

Primary Storage

1 TB 5400 rpm SATA ¹¹ 500 GB 5400 rpm SATA ¹¹

Primary M.2 Storage

1 TB PCIe[®] NVMe[™] M.2 SSD ¹¹ 512 GB PCIe[®] NVMe[™] M.2 SSD ¹¹ 256 GB PCIe[®] NVMe[™] M.2 SSD ¹¹ 128 GB PCIe[®] NVMe[™] M.2 SSD ¹¹

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows) is reserved for system recovery software.

MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM 12

Memory

32 GB DDR4-3200 SDRAM (2 x 16 GB) ¹² 16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹² 16 GB DDR4-3200 SDRAM (2 x 8 GB) ¹² 12 GB DDR4-3200 SDRAM (1 x 8 + 1 x 4GB) ¹² 8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹² 8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹² 4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹²

Memory Slots 13

2 SODIMM Both slots are customer non-accessible / non-upgradeable Supports Dual Channel Memory

Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.
 All slots are non-accessible / non-upgradeable.



NETWORKING/COMMUNICATIONS

WLAN

Realtek 8852BE Wi-Fi[®] 6 Bluetooth[®] 5.2 WLAN ¹⁴ Realtek 802.11b/g/n/a/ac (2x2) MU-MIMO supported and Bluetooth[®] 5 ¹⁵

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

AUDIO/MULTIMEDIA

Audio Dual Speakers Integrated dual array microphone

Speaker Power

2W/4ohm Per speaker

Camera

720p HD camera with Temporal Noise Reduction ⁷

7. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Island-style ash silver backlit keyboard with numeric keypad and touchpad with image sensor ¹⁶ Island-style ash silver keyboard with numeric keypad and Touchpad with image sensor

Pointing Device

Touchpad with multi-touch gesture support

Function Keys

ESC

- F1 help
- F2 Brightness Down
- F3 Brightness Up
- F4 Backlight Toggle
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Plays the previous track of an audio CD or the previous section of a DVD or a Blu-ray Disc (BD).
- F9 Starts, pauses, or resumes playback of an audio CD, a DVD, or a BD
- F10 Plays the next track of an audio CD or the next section of a DVD or a BD
- F11 Display Switching
- F12 Insert



16. Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

Software

Microsoft Office 2019 and Office 365 WPS Office CMIT **Dropbox Promotion** HP OuickDrop 17 MYOfficesMedio True DVD for HP Adobe offer **MvHP HP Privacy Settings HP SUPPORT ASSISTANT 18 HP** Audio Switch **HP** Connection Optimizer **ENERGY STAR® UWP HP PC Hardware Diagnostics Windows HP PC Hardware Diagnostics UEFI HP Smart Health HP Smart**

Manageability Features

Touchpoint Customizer for Consumer

NOTE: To enhance brightness, level go to the Intel[®] Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management

McAfee Security (30 days free trial as default) ¹⁹ Express VPN (30 days free trial) LastPass password manager TPM2.0 (select model) / TPM 1.4 ²⁰ Fingerprint Reader ²¹

Security TPM

fTPM 2.0 support

IPv6 Support Yes

FirstNet Certified No

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.8B Class: 3



17. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

18. HP Support Assistant requires Windows and Internet access.

19. 30-day McAfee[®] LiveSafe[™] trial included. Internet access required and not included. Subscription required after expiration. See www.McAfee.com for more details.

20 Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

21. HP Fingerprint sensor is an optional feature that must be configured at purchase.

POWER

Power Supply

HP Smart 65 W External AC power adapter ²² HP Smart 45 W External AC power adapter ²² Compliant with UL 1642 Standard

Battery

HP Long Life 3-cell, 41 Wh Li-ion ²³²⁵ Compliant with UL 1642 Standard

Power Cord 1M length Power Cord

Battery Life Up to 7 hours 5 minutes ²⁶

Battery Weight 175g +/-10g

22. Availability may vary by country.

23. Battery is internal and not replaceable by customer. Serviceable by warranty.

25. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

26. MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Product Weight²⁷ Starting at 4.6 lb Starting at 2.08 kg

Product Dimensions (w x d x h)

15.77 x 10.14 x 0.78 in 40.07 x 25.78 x 1.99 cm

27. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Ports

2 SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1) 1 HDMI 1.4 ²⁸ 1 SuperSpeed USB Type-C[®] 5Gbps signaling rate (Data Transfer Only) 1 AC power 1 Headphone/microphone combo jack

Expansion Slots

Push-Pull Insertion/Removal

28. HDMI cable sold separately.



SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90-day software support depending on country. Batteries have a default one year limited warranty. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. Onsite service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.²⁹

29. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	
Nominal Operating Voltage	19.5 V
Average Operating Power	7.69W (TBC)
Integrated graphics	Yes
Discrete Graphics	N/A (Switchable graphics design)
Max Operating Power	Discrete < 65W UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%
Shock	
Operating	40 G, 2 ms duration, half-sine
Non-operating	240 G, 2 ms duration, half-sine
Random Vibration	
Operating	1.043 grams
Non-operating	3.5 grams
Altitude (unpressurized)	
Operating	-15 m to 3048 m (-50 ft to 10000 ft)
Non-operating Planned Industry Standard	-15 m to 12192 m (-50 ft to 40000 ft)
Certifications	
Regulatory Model Number	TPN-I139
UL	Yes
CSA	No
FCC Compliance	Yes
ENERGY STAR [®]	Yes ³⁰
EPEAT	Yes, Gold in United States ³¹
ICES	Yes
Australia /	No
NZ A-Tick Compliance	No
CCC	Yes
Japan VCCI Compliance	No
KC	No
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	No
CIT	No
GOST	No
Saudi Arabian Compliance (ICCP)	No
SABS	No



Technical Specifications

UKRSERTCOMPUTER

No

30. Configurations of the HP 470 G9 17 inch Notebook PC that are ENERGY STAR[®] certified are identified as HP 470 G9 17 inch Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.
31. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

	17.3 inch FHD (1920x1080) Anti-Glare WLED UWVA 72percent cg 300nits eDP 1.2	Outline Dimensions (W x H x D)	390.190 x 238.810 (max.)	
		Active Area	381.888 x 214.812 (typ.)	
	w/o PSR slim 60Hz NWBZ	Weight	510 g(max)	
		Diagonal Size	17.3 (inch)	
		Thickness	3.5mm max.	
		Interface	eDP 1.2	
		Surface Treatment	Anti-Glare	
		Touch Enabled	No	
		Contrast Ratio	1000:1 (typ) 60Hz 300nits typ.	
		Refresh Rate		
		Brightness		
		Pixel Resolution - Format	1920 x 1080 (FHD)	
		Backlight	WLED	
		Pixel Resolution	RGB	
		Color Gamut Coverage	NTSC72%	
		Color Depth	8bits	
		Viewing Angle	UWVA 85/85/85/85	
		Low Blue Light	No	
		Power Consumption (W, EBL@ 150nits max/ 200nits max)	3.2 (max)/3.64 (max)	
	17.3 in HD+ (1600 x 900) Anti- Glare LED SVA NTSC 60 250 eDP	Outline Dimensions (W x H x D)	390.180 x 237.020 (max)	
	1.2 w/o PSR NWBZ flat Panel	Active Area	382.080 x 214.920 mm(typ.)	
		Weight	480 g(max)	

Diagonal Size

Surface Treatment

Pixel Resolution - Format

Touch Enabled

Contrast Ratio

Refresh Rate

Brightness

Backlight

Thickness

Interface

17.3 (inch)

Anti-Glare

500:1 (typ)

250nits typ.

1600x900 (HD+)

No

60Hz

WLED

3.5mm (max) eDP 1.2



	Pixel Resolution	RGB
	Color Gamut Coverage	NTSC60%
	Color Depth	6 bits
	Viewing Angle	45/45/20/40
	Low Blue Light	No
	Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.74 (max)/ 3.42(max)
17.3 in FHD (1920 x 1080) Anti-	Outline Dimensions (W x H x D)	390.190 x 238.810 (max)
Glare LED UWVA NTSC 45 250	Active Area	381.890 x 214.810 mm (typ.)
eDP 1.2 w/o PSR NWBZ flat Panel	Weight	500 g (max)
	Diagonal Size	17.3
	Thickness	3.5 (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	800:1 (typ)
	Refresh Rate	60Hz
	Brightness	250 nits (typ.)
	Pixel Resolution - Format	1920 x 1080 (FHD)
	Backlight	WLED
	Pixel Resolution	RGB
	Color Gamut Coverage	NTSC45%
	Color Depth	8 bits
	Viewing Angle	UWVA 85/85/85/85
	Low Blue Light	No
	Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.9W/3.5W



STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows) is reserved for system recovery software.

24528 - HDD 1TB 5400RPM	Drive Weight	0.21 lbs (95 g)		
7mm SATA (HDD 1TB	Rotation speed	5400rpm Up to 128MB		
5400RPM 2.5in)	Cache Buffer			
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	600 MB/s		
		Single Track: 2 ~ 1.5 ms;		
	Seek Time	Average: 11 ~ 13 ms;		
		Maximum: 18 ~ 22 ms		
	Logical Blocks	1,953,525,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
	Security Features	ATA Security		
	Features	S.M.A.R.T., NCQ, Ultra DMA		
16930 - HDD 500GB	Drive Weight	0.21 lbs (95 g)		
5400RPM 7mm SATA	Rotation speed	5400rpm		
	Cache Buffer	Up to 128MB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	600 MB/s		
		Single Track: 2 ~ 1.5 ms;		
	Seek Time	Average: 11 ~ 13 ms;		
		Maximum: 18 ~ 22 ms		
	Logical Blocks	976,773,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]		
	Security Features	ATA Security		
	Features	S.M.A.R.T., NCQ, Ultra DMA		
50209 - SSD 128GB 2230	Form Factor	M.2 2230		
PCIe NVMe Value (SSD	Capacity	128GB		
128GB 2230 PCIe NVMe	NAND Type	value		
Value)	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe		
	Maximum Sequential Read			
	Maximum Sequential Write			
	Logical Blocks	250,069,680		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		



Technical Specifications

	Features	Pyrite			
7426 660 42060 2200					
57426 - SSD 128GB 2280 PCle-3x2 Three Layer	Form Factor	M.2 2280			
Cell (SSD 128GB 2280 PCIe-	Capacity	128GB			
8x2 Three Layer Cell)	NAND Type	TLC			
	Height	0.09 in (2.3 mm)			
	Width	0.87 in (22 mm)			
	Interface	PCIe NVMe Gen3X4			
	Maximum Sequential Read				
	Maximum Sequential Write				
	Logical Blocks	250,069,680			
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]			
	Features	Pyrite			
	Form Factor	M.2 2280			
51597 - SSD 1TB 2280 PCIe	Form Factor	M.2 2280			
IVMe Value (1TB 2280	Capacity	1TB			
Cle NVMe Value 2nd Solid	NAND Type	value			
State Drive)	Height	0.09 in (2.3 mm)			
	Width	0.87 in (22 mm)			
	Weight	0.67 m (22 mm)			
	Interface				
		PCIe NVMe			
	Maximum Sequential Read Maximum Sequential Write				
	Logical Blocks	2,000,409,264			
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]			
	Features	Pyrite			
7267 - SSD 256GB 2280	Faun Fachau	M 2 2200			
Cie NVMe Value (SSD	Form Factor	M.2 2280			
56GB 2280 PCIe NVMe	Capacity	256GB			
alue)	NAND Type	value			
-	Height	0.09 in (2.3 mm)			
	Width	0.87 in (22 mm)			
	Interface	PCIe NVMe			
	Maximum Sequential Read				
	Maximum Sequential Write				
	Logical Blocks	500,118,192			
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]			
	Features	Pyrite			



47268 - SSD 512GB 2280	Form Factor	M.2 2280
PCIe NVMe Value	Capacity	512GB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Maximum Sequential Read	
	Maximum Sequential Write	
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite



NETWORKING/COMMUNICATIONS

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + Bluetooth® 5 ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11i IEEE 802.11v
	Interoperability	Wi-Fi certified modules
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : max 866.7Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum



Technical Specifications

Power Consump	• Transmit mod	e ·2 0 W
i ower consum	Receive mode	
		P) 180 mW (WLAN Associated)
	• Idle mode :50	mW (WLAN unassociated)
	Connected Sta	andby/Modern Standby: 10mW
	 Radio disabled 	d: 8 mW
Power Manager	ment ACPI and PCI Ex	press compliant power management
	802.11 complia	nt power saving mode
Receiver Sensit	•	s : -93.5dBm maximum
		ps : -84dBm maximum
	_	ops : -86dBm maximum
		1bps : -72dBm maximum 7 : -67dBm maximum
		5 : -64dBm maximum
) : -84dBm maximum
		9 : -59dBm maximum
Antenna type	High efficiency a	antenna with spatial diversity, mounted in the display
	enclosure	
		dual band 2.4/5 GHz antennas are provided to the card to
	support WLAN N	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2	2 MiniCard
Dimensions	1. Type 2230 : 2	2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1	.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2	2.8g
	2. Type 126: 1.3	3g
Operating Volta	age 3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Ra	
-	LED OFF – Radio	
HP Integrated Module with Bluetooth 4.0/4	4.1/4.2/5.0 Wireless Techn	ology
Bluetooth Spec		•
Frequency Band		
Number of Avai Channels	ilable Legacy: 0~79 (1 BLE: 0~39 (2 Mł	
Data Rates and		data rate; throughput up to 2.17 Mbps
Throughput		ta rate; throughput up to 0.2 Mbps pnous Connection Oriented links up to 3, 64 kbps, voice
	channels	bildus connection onenteu links up to 5, 64 kops, voice
	Legacy: Asynch	ronous Connection Less links 2178.1 kbps/177.1 kbps
	-	DH5) or 864 kbps symmetric (3-EV5)
Transmit Powe		component shall operate as a Class II Bluetooth device with nsmit power of + 4 dBm for BR and EDR.
	a maximum li di	ייש איש איש איש איש איש איש איש איש איש

1. Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router.



Technical Specifications

Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852BE 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.2 (802.11ax 2x2, supporting gigabit data rate) ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified modules
	Frequency Band Data Rates	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac: max 866.7Mbps 802.11ax : max 1201Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)

Infrastructure (A	ccess Point Required)	
Infrastructure (Access Point Required)		
IEEE 802.11 compliant roaming between access points		
 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum 802.11n HT40(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 		
• 802.11ax HE80	(5GHz) : +10dBm minimum	
 Transmit mode :2.5 W Receive mode :2 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode :50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW 		
-	ress compliant power management t power saving mode	
802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE80): -54dBm maximum		
High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
PCI-Express M.2	MiniCard	
1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
1. Type 2230: 2.8g 2. Type 126: 1.3g		
3.3v +/- 9%		
Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)	
Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Amber – Rac LED Off – Radio (
	 802.11b : +18.5 802.11g : +17.5 802.11a : +18.5 802.11a : +18.5 802.11a : +18.5 802.11a : +18.5 802.11a : +18.6 802.11n HT20(802.11n HT40(802.11n HT40(802.11a VHT8 802.11a VHT8 802.11a × HE40 802.11a × HE40 802.11a × HE80 Transmit mode Receive mode : Idle mode (PSP Idle mode (PSP Idle mode (Son Connected Star Radio disabled: ACPI and PCI Exp 802.11 complian 802.11b, 11Mbps: 802.11a, MCS07 802.11a, fomp: 802.11a, fomp: 802.11a, MCS07 802.11a, MCS15 802.11a, MCS15 802.11a, MCS15 802.11a, MCS15 802.11a, MCS16 802.11a, MCS17 802.11a, MCS16 802.11a, MCS16 802.11a, MCS17 802.11a, MCS16 802.11a, MCS16 802.11a, MCS16 802.11a, MCS16 802.11a, MCS17 802.11a, MCS16 802.11a, MCS16 802.11a, MCS17 802.11a, MCS16 802.11a, MCS16 802.11a, MCS17 802.11a, MCS17 802.11a, MCS17 802.11a, MCS16 802.11a, MCS17 802.11a, MCS17<!--</td-->	



HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

HP 65W Smart AC	Dimensions (H x W x D)	3.54 x 2.0 x 1.122 in (9.0x5.1x2.85 cm)			
adapter	Weight	0.5 lb (230 g) max (Not including power cord. Power cord varies by country)			
	Input				
		Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac		
		Input frequency range	47 ~ 63 Hz		
		Input AC current	Max. 1.7 A at 90 Vac		
	Output	Output power	65W		
		DC output	19.5V		
		Hold-up time	5ms at 115 Vac input		
		Output current limit	<11.0A Over voltage protection- 29V max automatic shutdown		
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cord			
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)		
		Non-operating (storage)	-4°F to 185°F (-20° to 85°C)		
		temperature			
		Altitude	1 to 16,400 ft (0 to 5,000m)		
		Humidity	20% to 95%		
		Storage Humidity	10% to 95%		
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, IEC-62368, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.			
HP 45W Smart AC	Dimensions	3.74x1.77x1.04in(9.5x4.5.2.65cm)			
adapter	Weight Input	0.44 lb (200g) max (Not including power cord. Power cord varies by country)			
	mput	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac		
		Input frequency range	47 ~ 63 Hz		
	Output	Input AC current Output power	Max. 1.4 A at 90 Vac 45W		
		DC output	19.5V		
		Hold-up time	5ms at 115 Vac input		
		Output current limit	<8.0A		
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable			
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)		
	-	Non-operating (storage) temperature	-4ºF to 185ºF (-20ºto 85ºC)		
		Altitude	1 to 16,400 ft (0 to 5,000m)		



Technical Specifications Humidity 20% to 95% 10% to 95% **Storage Humidity EMI and Safety** Ea: Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950. IEC-62368. EN60950. UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 3-cell Long Life Li-Dimensions (H x W x L) 6.0 x 186.85 x 90.2 mm (0.234 x 7.35 x 3.55 inch) Ion (41 Wh¹) Weight 0.175 kg (0.385 lb) Cells/Type 3cell Lithium-Ion Polymer cell / 515974 Energy Voltage 11.34V / 11.28V Amp-hour capacity 3.62Ah / 3.635Ah Watt-hour capacity 41Wh Temperature **Operating (Charging)** 32° to 113° F (0° to 45° C) 14° to 122° F (-10° to 60° C) Operating (Discharging) **Fuel Gauge LED** N/A Warranty 1-year **Optional Travel** No **Battery Available**

Technical Specifications

AUDIO

HD Stereo Codec	Realtek ALC3247
Audio I/O Ports	One Headset Combo-Jack connector support CTIA spec.
Internal Speaker Amplifier	2W class D stereo amplifier for the internal speaker only. External speakers must be powered.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the Combo jack or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 48 kHz for DAC and ADC.
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes.
# of Channels on Line-Out	1
Internal Speaker	Yes

FINGERPRINT READER

Sensor vendor	Elan eFSA80ST touch sensor
Sensor type	Capacitive
DPI resolution	508 DPI
Scan area	80 x 80 pixels array
False Rejection Rate	FRR (False Reject Rate) / FAR (False Acceptance Rate):
False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption	FRR ~ 2% @ 1:50K FAR Mobile Voltage Operation: 2.65V to 3.6V Operating Temperature: 32° to 95° F (0° to 35° C)
lmage Low Latency Wait For Finger	Current Consumption Image: 50mA peak Low Latency Wait For Finger: <900 uA
Capture Rate	Capture Rate: 20cm/sec
ESD Resistance	ESD Resistance: IEC 61000-4-2 (+15KV)
Detection Matrix	Detection Matrix: 508 dpi / 4x4mm sensor area



ENVIRONMENTAL DATA

Eco-Label Certifications &	This product has received	or is in the process of being c	ertified to the following approvals and may	
declarations	be labeled with one or more of these marks:			
	IT ECO declaration			
	US ENERGY STAR®			
		y Management Program (FEN	МР)	
			ee http://www.epeat.net for registration	
	status in your cou			
	-	servation Program (CECP)		
		onmental Protection Adminis	stration (SEPA)	
	Taiwan Green Mar			
	Korea Eco-label			
	Japan PC Green la	ibel*		
Sustainable Impact		Speaker, Bezel and Cover		
Specifications	 5% post-consumer recyc 	•		
• • • • • • • •	Low halogen	F		
	-	ted cushions are 100% susta	ainably sourced and recyclable	
	-		nably sourced and recyclable	
System Configuration			and Declared Noise Emissions data for the	
		on a "Typically Configured N		
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Sort				
idle)	9.5 W	9.47 W	10.85 W	
Normal Operation (Long				
idle)	0.93 W	1.09 W	0.94 W	
Sleep	0.93 W	1.09 W	0.94 W	
Off	0.32 W	0.34 W	0.3 W	
	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered with family. HP computers marked with the ENERGY STAR® Logo are compliant with the ap Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers family does not offer ENERGY STAR® compliant configurations, then energy efficience is for a typically configured PC featuring a hard disk drive, a high efficiency power s Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short	_,	-,		
idle)	32.5 BTU/hr	32.4 BTU/hr	37.1 BTU/hr	
Normal Operation (Long				
idle)	3.2 BTU/hr	3.7 BTU/hr	3.2 BTU/hr	
Sleep	3.2 BTU/hr	3.7 BTU/hr	3.2 BTU/hr	
Off	1.1 BTU/hr	1.2 BTU/hr	1 BTU/hr	
	*NOTE: Heat dissipation is attained for one hour.	calculated based on the me	asured watts, assuming the service level is	



Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{WAd} , bels)			Sound P (L _{pAm} , de	
Typically Configured – Idle		1.8			17	.5
Fixed Disk – Random writes		1.8			17	
Optical Drive – Sequential reads		1.8			21	.0
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the					
	Spare parts a of production		ighout the	warranty period a	nd or for up	o to "5" years after the end
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product is 96.6% recycle-able when properly disposed of at end of life. 					
Packaging Materials	External:	PAPER/Corruga	ted			326 g
		PAPER/Molded	Pulp			201 g
	Internal:	PLASTIC/Polyet	hylene lov	v density - LDPE		17 g
		PLASTIC/Polypropylene - PP			5 g	
	The plastic packaging material contains at least 0.0% recycled content.					
	The corrugated paper packaging materials contains at least 55.6% recycled content.					
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.					
Material Usage	This product to the		any of the neral	following substan Specification	ces in exces for	ss of regulatory limits (refer the Environment at



	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (DBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DBP) Diisobutyl phthalate (DBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl (PBBS) Polybrominated Biphenyl (PCB) Polychorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly



Technical Specifications

	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporat Environmental	e For more information about HP's commitment to the environment:
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials.

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Renew Business 17.3" Backpack	3E2U5AA
	HP Renew Business 17.3" Bag	3E2U6AA
Hub	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB 3.0 to Gigabit Adapter	N7P47AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP HDMI to VGA Adapter	H4F02AA
Keyboard/Combo	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
	HP 155 Wired Mouse and Keyboard Combo	5B8COAA#ACJ
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 125 USB-A Wired Mouse	265A9AA
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
	HP 235 Slim Wireless Mouse	4E407AA
	HP 155 USB-A Wired Mouse	5B8B7AA#ACJ
	HP USB-A Travel USB Mouse	G1K28AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1DOK2AA
Power	HP 65W Smart AC Adapter	Н6Ү89АА
	HP 45W 4.5 mm Smart AC Power Adapter	H6Y88AA
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA



Summary of Changes

Date of change	Version History	Description of change
	V1 to V2	

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